



4/20/05

04-25-2005

P/4076-100

PATENTS I



HEET

102987705

To the Director of the U.S. Patent and Trademark Office: Please record the attached original document or copy thereof.

1. Name of conveying party(ies): Xiang CHEN Shu Chuen HO Teng Hock Eric KUAH Si Liang LU See Yap ONG  Type of Entity: Individual		2. Name and Address of receiving party(ies): ASM Technology Singapore Pte Ltd. 2 Yishun Avenue 7 Singapore 768924  Type of Entity: Corporation-Singapore	
Additional names(s) of conveying party(ies) attached? No		Additional name(s) & address(es) attached? No	
3. Nature of Conveyance: Assignment  Execution Date: April 2, 2005; February 4, 2005; February 4, 2005; March 21, 2005; March 21, 2005, respectively			
4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is:			
A. Application No.(s) 11/052,566		B. Patent No.(s)	
Additional numbers attached? No			
5. Name and address of party to whom correspondence concerning document should be mailed:  OSTROLENK, FABER, GERB & SOFFEN, LLP 1180 Avenue of the Americas New York, New York 10036-8403		6. Total number of documents involved: 1	
		7. Total fee (37 CFR 3.41): \$ 40.00	
		Enclosed as part of Check No. 20274	
In the event the actual fee is greater than the payment submitted or is inadvertently not enclosed or if any additional fee due is not paid, the Patent and Trademark Office is authorized to charge the underpayment to Deposit Account No. 15-0700.			
DO NOT USE THIS SPACE			
04/21/2005 MAHME1 00000008 11052566		40.00 DP	
8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.			
Robert C. Faber Name of Person Signing		[Signature] Signature	April 15, 2005 Date
Total number of pages including cover sheet, attachments, and document: 2			

00695481.1

WHEREAS, I (We), Xiang CHEN, Shu Chuen HO, Teng Hock Eric KUAH, Si Liang LU, and See Yap ONG as assignor(s), have invented certain improvements in APPARATUS AND PROCESS FOR MOLDING WITH REDUCED CULL FORMATION for which an application for United States Letters Patent has been executed by me (us) of even date herewith; and

WHEREAS, ASM Technology Singapore Pte Ltd, a corporation organized and existing under the laws of Singapore and having a principal place of business at 2 Yishun Avenue 7, Singapore 768924 as assignee, is desirous of acquiring all right, title and interest in and to said invention and any Patent that may be granted therefor.

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt of which is hereby acknowledged, I (We), as assignor(s), hereby sell, assign and set over to said assignee the entire right, title and interest for the United States and all other countries in and to said invention and the aforesaid application for Patent, all original, divisional, continuation, substitute or reissue applications and patents applied for or granted therefor in the United States and all other countries, including all rights of priority from the filing of said application, and all rights for past infringement, and the Commissioner of Patents and Trademarks is hereby authorized and requested to issue all patents on said inventions or resulting therefrom to said assignee herein, as assignee of the entire interest therein; and the undersigned for myself (ourselves) and my (our) legal representatives, heirs and assigns do hereby agree and covenant without further remuneration, to execute and deliver all divisional, continuation, reissue and other applications for Patent on said inventions and all assignments thereof to said assignee or its assigns, to communicate to said assignee or its representatives all facts known to the undersigned respecting said inventions, whenever requested, to testify in any interferences or other legal proceedings in which any of said applications or patents may become involved, to sign all lawful papers, make all rightful oaths, and to do generally everything necessary to assist assignee, its successors, assigns and nominees to obtain patent protection for said invention in the United States and all other countries, the expenses incident to said applications to be borne and paid by said assignee.

Date: 4/2/2005

Chen Xiang  
Xiang CHEN

Date: Feb 4, 2005

Shu Chuen HO  
Shu Chuen HO

Date: FEB 4, 2005

Teng Hock Eric KUAH  
Teng Hock Eric KUAH

Date: 21/03/05

Si Liang LU  
Si Liang LU

Date: 21/03/05

See Yap ONG  
See Yap ONG